

Amendment to the Abstract

Please delete the abstract and replace it with the following:

-- ~~Disclosed are m~~Methods for depositing a ~~conductive seed~~ layer on a substrate having a barrier layer and/or a dielectric layer are provided. Also provided are methods of enhancing discontinuous seed layers. Such methods are achieved by the use of conductive polymers and are particularly suitable for depositing an electroplated copper layer on a substrate having small apertures, and preferably very small apertures. --